

Notice of References Cited	Application/Control No. 10/784,324	Applicant(s)/Patent Under Reexamination NUYTKENS ET AL.	
	Examiner Paul D. Kim	Art Unit 3729	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,228,768	05-2001	Woo et al.	438/691
*	B	US-5,228,313	07-1993	Okamoto et al.	62/407
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	"Application of via post interconnection for build up printed circuit board"; Kobayashi, T.; Itaya, S.; Ikeda, K.; Kawasaki, J.; Honma, H.; IEMT/IMC Symposium, 2nd 1998; 15-17 April 1998; Pages:312 - 315.
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.